

KL 6000 series – run sheet

KemLab Inc.

nanyte.com/photoresists/kl-6000 · last updated 2026-07-26

Thickness: 2.5–12 μm

Softbake: 105 °C · 2 min · hotplate

Post-exposure bake: 90 °C · 1.5 min

Develop: Developer 0.26N TMAH